

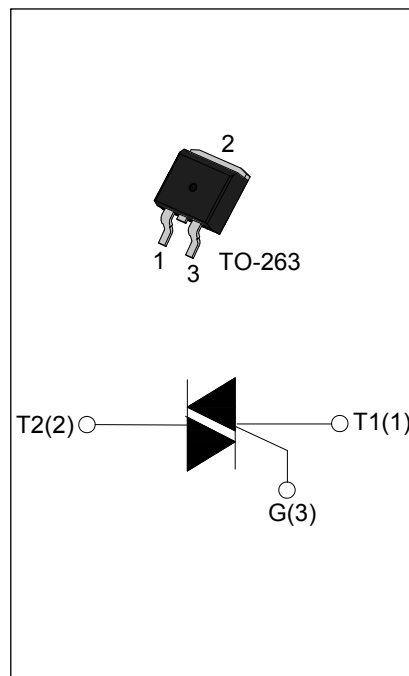


### DESCRIPTION:

T20xxH triacs, with high ability to withstand the shock loading of large current, provide high dv/dt rate with strong resistance to electromagnetic interference. With high commutation performances, 3 quadrants products especially recommended for use on inductive load. Package TO-263 is RoHS compliant. (2011/65/EU)

### MAIN FEATURES

Symbol	Value	Unit
$T_j$	150	°C
$I_{T(RMS)}$	20	A
$V_{DRM}/V_{RRM}$	600/800	V



### ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		$T_{stg}$	-40-150	°C
Operating junction temperature range		$T_j$	-40-150	°C
Repetitive peak off-state voltage		$V_{DRM}$	600/800	V
Repetitive peak reverse voltage		$V_{RRM}$	600/800	V
RMS on-state current	TO-263 ( $T_C=65^\circ\text{C}$ )	$I_{T(RMS)}$	20	A
Non repetitive surge peak on-state current (full cycle, F=50Hz)		$I_{TSM}$	200	A
$I^2t$ value for fusing ( $t_p=10\text{ms}$ )		$I^2t$	200	$\text{A}^2\text{s}$
Critical rate of rise of on-state current ( $I_G=2 \times I_{GT}$ )		$di/dt$	100	$\text{A}/\mu\text{s}$
Peak gate current		$I_{GM}$	4	A
Average gate power dissipation		$P_{G(AV)}$	1	W
Peak gate power		$P_{GM}$	10	W

**ELECTRICAL CHARACTERISTICS** ( $T_j=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Test Condition	Quadrant		Value		Unit
				T2035H	T2050H	
$I_{GT}$	$V_D=12\text{V } R_L=33\Omega$	I - II -III	MAX	35	50	mA
$V_{GT}$		I - II -III	MAX	1.5		V
$V_{GD}$	$V_D=V_{DRM} T_j=150^{\circ}\text{C}$ $R_L=3.3\text{K}\Omega$	I - II -III	MIN	0.2		V
$I_L$	$I_G=1.2I_{GT}$	I -III	MAX	50	70	mA
		II		60	80	
$I_H$	$I_T=100\text{mA}$		MAX	40	60	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=150^{\circ}\text{C}$		MIN	250	500	V/ $\mu\text{s}$
(dV/dt) <sub>c</sub>	(dI/dt) <sub>c</sub> =8.8A/ms $T_j=150^{\circ}\text{C}$		MIN	7	15	V/ $\mu\text{s}$

**STATIC CHARACTERISTICS**

Symbol	Parameter		Value(MAX)	Unit
$V_{TM}$	$I_{TM}=28\text{A } t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.55	V
$I_{DRM}$	$V_D=V_{DRM} V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	5	$\mu\text{A}$
$I_{RRM}$		$T_j=150^{\circ}\text{C}$	2.5	mA

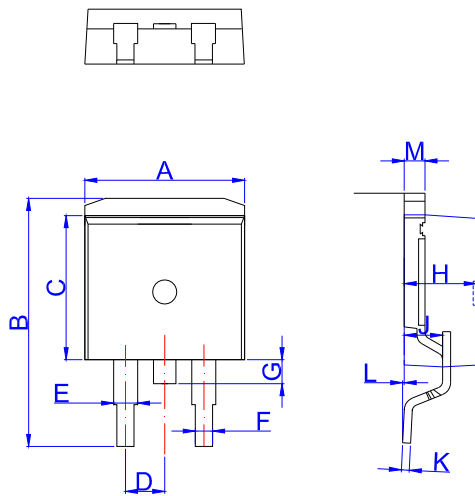
**THERMAL RESISTANCES**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-263	2.8	$^{\circ}\text{C/W}$
$R_{th(j-a)}$	junction to ambient		45	

**ORDERING INFORMATION**

<b>T</b> Triacs 20: $T_{(RMS)}:20\text{A}$ 35: GT1-3 35 50: $I_{GT1-3} \leq 50\text{mA}$	<b>20</b>	<b>35</b>	<b>H</b> H: $T_j=150^{\circ}\text{C}$	<b>-6</b>	<b>E</b> E: TO-263 ETR: TO-263(Tape&Reel) 6: $V_{DRM}/V_{RRM} \geq 600\text{V}$ 8: $V_{DRM}/V_{RRM} \geq 800\text{V}$
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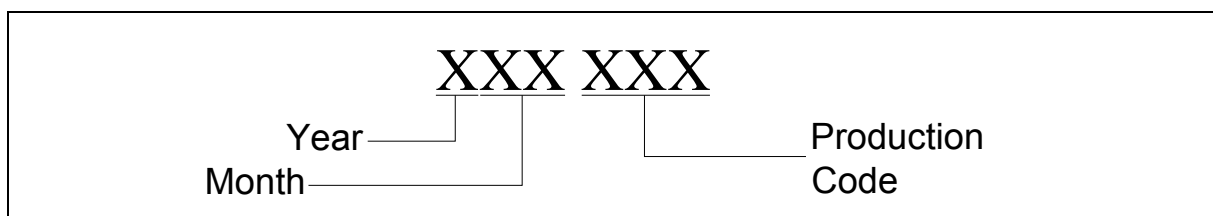
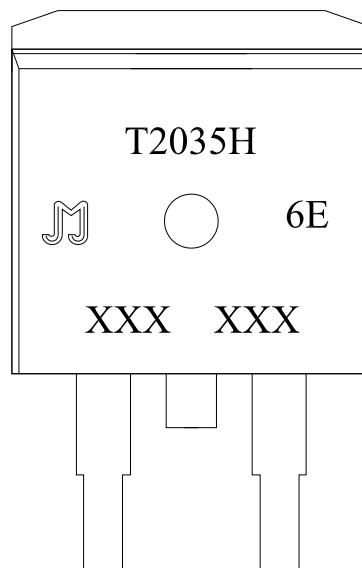
PACKAGE MECHANICAL DATA



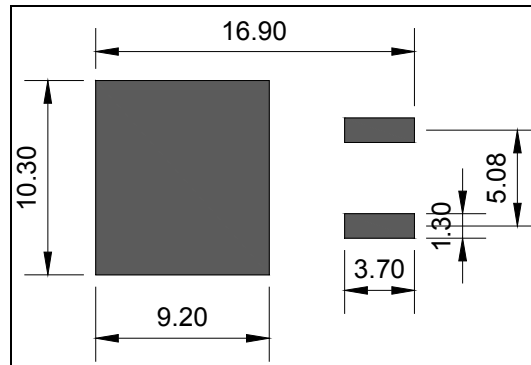
TO-263

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

MARKING



FOOTPRINT-TO-263 (dimensions in mm)



PACKAGE INFORMATION

PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	6,000
TO-263	TUBE	50	1,000	8,000
PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
TO-263	TAPING	800	4,000	13 inch

FIG.1: Maximum power dissipation versus RMS on-state current

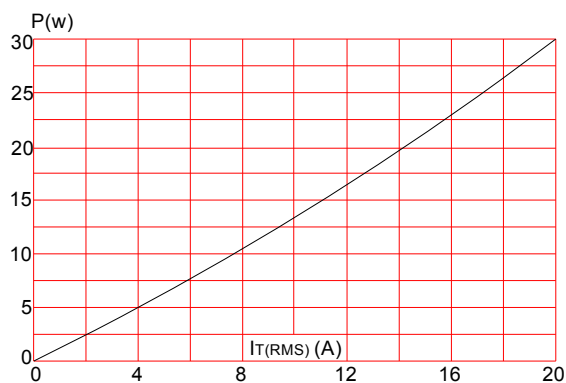
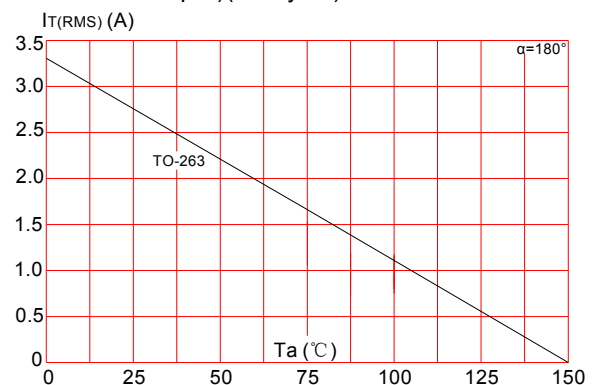
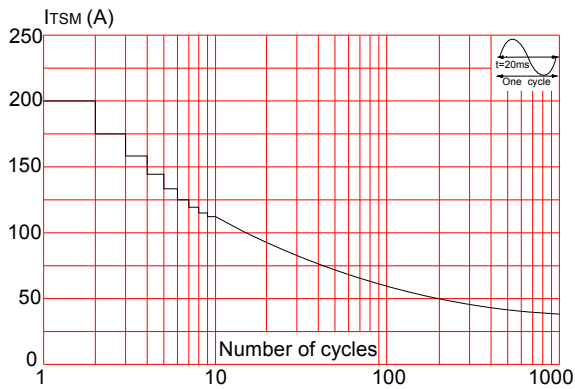


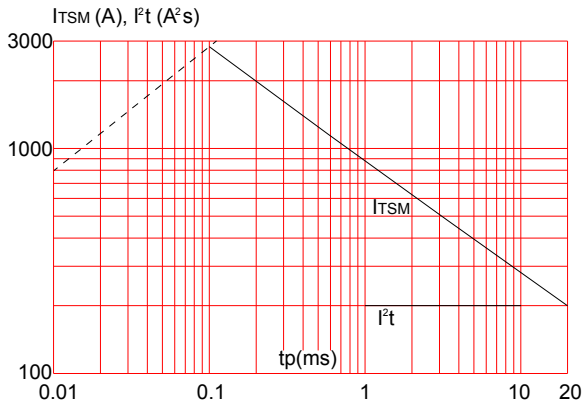
FIG.2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness:35 $\mu$ m)(full cycle)



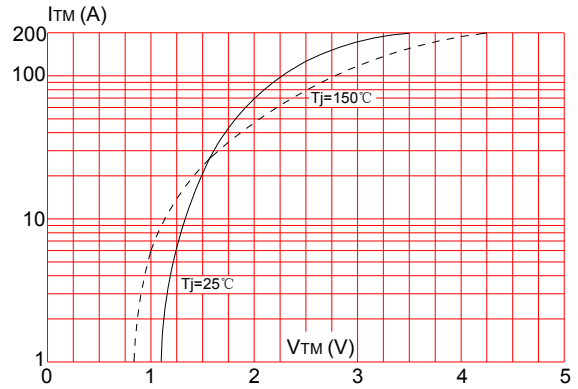
**FIG.3:** Surge peak on-state current versus number of cycles



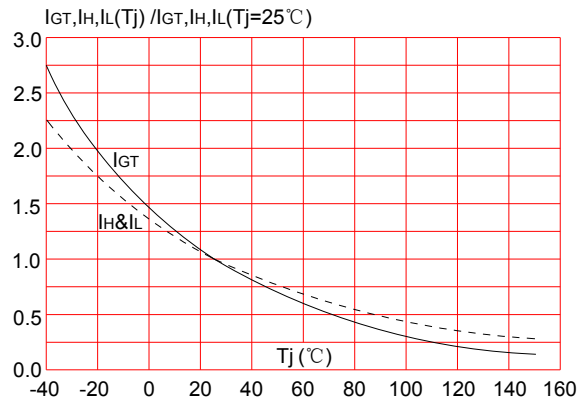
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20ms$ , and corresponding value of  $I^2t$  ( $di/dt < 100A/\mu s$ )



**FIG.4:** On-state characteristics (maximum values)

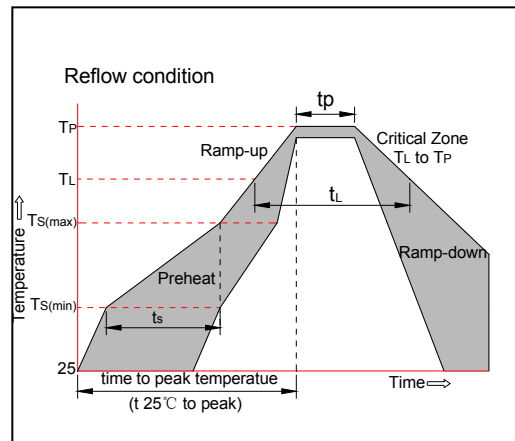


**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature




**SOLDERING PARAMETERS**

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max ( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquidus)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C



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